

## MSC2X31/30SDA120J Dual Silicon Carbide Schottky Barrier Diodes

## **Product Overview**

The silicon carbide (SiC) power Schottky barrier diode (SBD) product line from Microsemi increases the performance over silicon diode solutions while lowering the total cost of ownership for high-voltage applications. MSC2X31/30SDA120J are dual 1200 V, 30 A SiC SBD devices in a SOT-227 package.

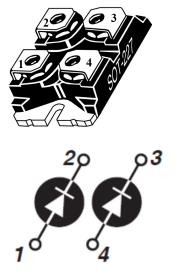


Figure 1 • Parallel MSC2X31SDA120J

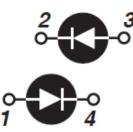


Figure 2 • Anti-parallel MSC2X30SDA120J

### **Features**

The following are key features of the MSC2X31SDA120J and MSC2X30SDA120J devices:

- No reverse recovery
- Low forward voltage
- Low leakage current
- Avalanche-energy rated
- RoHS compliant
- Isolated voltage to 2500 V

### **Benefits**

The following are benefits of the MSC2X31SDA120J and MSC2X30SDA120J devices:

- Outstanding performance at high-frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction-to-case thermal resistance
- RoHS compliant



## **Applications**

The MSC2X31SDA120J and MSC2X30SDA120J devices are designed for the following applications:

- Power factor correction (PFC)
- Anti-parallel diode
  - Switch-mode power supply
  - Inverters/converters
  - Motor controllers
- Freewheeling diode
  - Switch-mode power supply
  - Inverters/converters
- Snubber/clamp diode



## **Device Specifications**

This section shows the specifications of the MSC2X31SDA120J and MSC2X30SDA120J devices.

### **Absolute Maximum Ratings**

The following table shows the absolute maximum ratings per diode of the MSC2X31SDA120J and MSC2X30SDA120J devices.  $T_c = 25$  °C unless otherwise specified.

#### Table 1 • Absolute Maximum Ratings

Symbol	Parameter		Ratings	Unit
V <sub>R</sub>	Maximum DC reverse voltage		1200	v
I <sub>F</sub>	Maximum DC forward current	T <sub>C</sub> = 100 °C	30	A

The following table shows the thermal and mechanical characteristics of the MSC2X31SDA120J and MSC2X30SDA120J devices.

Symbol	Characteristics	Min	Тур	Max	Unit
R <sub>OJC</sub>	Junction-to-case thermal resistance		0.60	0.87	°C/W
VISOLATION	RMS voltage (50 Hz–60 Hz sinusoidal waveform from terminals to mounting base for 1 minute)	2500			V
T <sub>J</sub> , T <sub>STG</sub>	Operating junction and storage tempera- ture range	-55		175	°C
Wt	Package weight		1.03		OZ
			29.2		g
	Mounting torque, M4 screw			10	lbf-in
				1.1	N-m

#### Table 2 • Thermal and Mechanical Characteristics



## **Electrical Performance**

The following table shows the static characteristics per diode of the MSC2X31SDA120J and MSC2X30SDA120J devices.  $T_J = 25$  °C unless otherwise specified.

Table 3 • Static Characteristics Per Diode

Symbol	Characteristics	Test Conditions		Min	Тур	Max	Unit
V <sub>F</sub>	Forward voltage	I <sub>F</sub> = 30 A			1.5	1.8	V
			T <sub>J</sub> = 175 °C		2.1		
I <sub>RM</sub>	Reverse leakage current $V_R = 1200 V$	V <sub>R</sub> = 1200 V			9	200	μΑ
			T <sub>J</sub> = 175 °C		150		
Q <sub>c</sub>	Total capacitive charge	V <sub>R</sub> = 600 V			130		nC
Cj	Junction capacitance	V <sub>R</sub> = 400 V, f = 1 MHz V <sub>R</sub> = 800 V, f = 1 MHz			141		pF
					105		



## **Typical Performance Curves**

This section shows the typical performance curves per diode of the MSC2X31SDA120J and MSC2X30SDA120J devices.

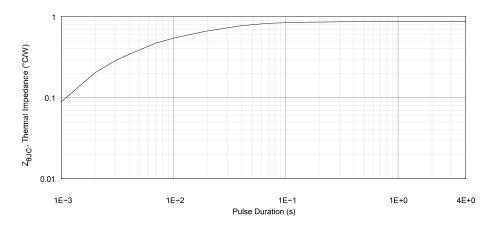


Figure 3 • Maximum Transient Thermal Impedance

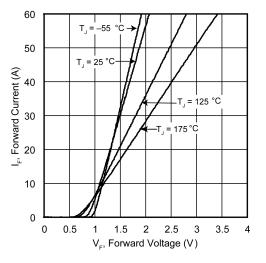
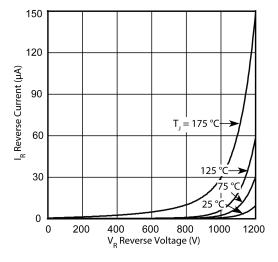


Figure 4 • Forward Current vs. Forward Voltage





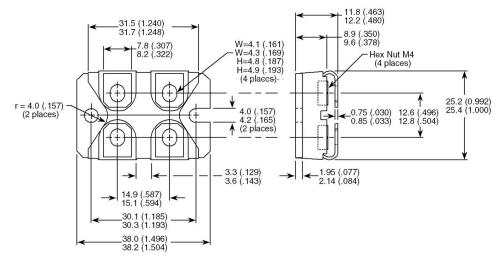


## **Package Specification**

This section shows the package specification of the MSC2X31SDA120J and MSC2X30SDA120J devices.

## Package Outline Drawing

The following figure illustrates the SOT-227 package outline of the MSC2X31SDA120J and MSC2X30SDA120J devices. The dimensions in the following figure are in millimeters and (inches).



Dimensions in Millimeters and (Inches)

Figure 6 • Package Outline Drawing





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